



Product Change Notification: BLAS-01LHKC373

Date:

06-Oct-2025

Product Category:

Memory

Notification Subject:

CCB 7235.001 Final Notice: Qualification of AMK-EP27 as an additional die attach material, AMK-MC27 as an additional molding compound material and CuPdAu as an additional wire material for AT25M01-SSHM-T and AT25M01-SSHM-B catalog part numbers (CPN) available in 8L SOIC (.150in) package.

Affected CPNs:

[BLAS-01LHKC373_Affected_CPN_10062025.pdf](#)

[BLAS-01LHKC373_Affected_CPN_10062025.csv](#)

PCN Status: Final Notification

PCN Type: Manufacturing Change

Microchip Parts Affected: Please open one of the files found in the Affected CPNs section.
Note: For your convenience Microchip includes identical files in two formats (.pdf and .xls)

Description of Change: Qualification of AMK-EP27 as an additional die attach material, AMK-MC27 as an additional molding compound material and CuPdAu as an additional wire material for AT25M01-SSHM-T and AT25M01-SSHM-B catalog part numbers (CPN) available in 8L SOIC (.150in) package.

Pre and Post Summary Changes:

| | Pre Change | Post Change | |
|----------------------|--|--|--------|
| Assembly Site | Amkor Technology Philippine (P1/P2), INC. (ANAP) | Amkor Technology Philippine (P1/P2), INC. (ANAP) | |
| Wire Material | PdCu | PdCu | CuPdAu |

| | | | |
|----------------------------------|-------------|-------------|-------------------------|
| Die Attach Material | 8290 (PFAS) | 8290 (PFAS) | AMK-EP27 (PFAS-free) |
| Molding Compound Material | G700A | G700A | AMK-MC27 |
| Lead-Frame Material | C194 | C194 | C19400FH |
| DAP Surface Prep | PPF | PPF | Ring Ag |

Impacts to Datasheet: None

Change Impact: None

Reason for Change: To improve manufacturability by qualifying 66.9k wafer technology with AMK-EP27 as a new die attach material and CuPdAu as a new wire material.

Change Implementation Status: In Progress

Estimated First Ship Date: 24 December 2025 (date code: 2552)

Note Below EFSD: Note: Please be advised that after the estimated first ship date customers may receive pre and post change parts.

Timetable Summary:

| | October 2025 | | | | | > | December 2025 | | | | |
|--------------------------------------|--------------|----|----|----|----|---|---------------|----|----|----|----|
| Work Week | 40 | 41 | 42 | 43 | 44 | | 49 | 50 | 51 | 52 | 01 |
| Qual Report Availability | | x | | | | | | | | | |
| Final PCN Issue Date | | x | | | | | | | | | |
| Estimated Implementation Date | | | | | | | | | x | | |

Method to Identify Change: Traceability Code

Qualification Report: Please open the attachments included with this PCN labeled as PCN_{#}_Qual_Report.

Revision History: October 07, 2025: Issued final notification.

Note: The change described in this PCN does not alter Microchip's current regulatory compliance regarding the material content of the applicable product.

Attachments:

[**PCN_BLAS-01LHKC373 Qual Report.pdf**](#)

Please contact your local [**Microchip sales office**](#) with questions or concerns regarding this notification.

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